A2696 BOARD SPECIFICATIONS

1. Board Layers: 10
2. Layer Stack Order:
   - Layer1 (Artwork_1): Top component layer, Filled with solid ground 0.5oz
   - Layer2 (Artwork_2): signal_3, 0.5oz, Z(diff)=100ohm
   - Layer3 (Artwork_3): Ground, Drawing_1, 1oz
   - Layer4 (Artwork_4): signal_4, 0.5oz, Z(diff)=100ohm
   - Layer5 (Artwork_5): Ground, drawing_2 1oz
   - Layer6 (Artwork_6): Ground, Drawing_1 1oz
   - Layer7 (Artwork_7): signal_5, 0.5oz, Z(diff)=100ohm
   - Layer8 (Artwork_8): Ground, drawing_2 1oz
   - Layer9 (Artwork_9): signal_6, 0.5oz, Z(diff)=100ohm
   - Layer10 (Artwork_8): Bottom component layer, Filled with solid ground, 0.5oz
3. Apply silkscreen on both Top and Bottom component side:
   - Artwork_9: Top silkscreen.
   - Artwork_10: Bottom silkscreen.
4. Apply solder mask over bare copper on both side:
   - Artwork_11: two layers epoxy (2-3u) top solder mask.
   - Artwork_12: two layers epoxy (2-3u) bottom solder mask.
5. Material: FR4
6. Board thickness: 0.120'' +/- 0.010.
7. Minimum Diff. Trace/gap/trace= 7/5/7 mils
8. Trace impedance control: 100 ohms +/-10% for all differential 7/5/7 pairs.
9. Board finish type: IM-TIN
10. All dimensions are in inches unless otherwise noted.

Please note top and bottom layer are also ground planes.

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